

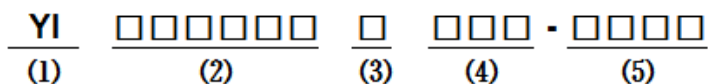
■ Features

- High density packaging with a pitch of 2.54mm(0.1 inch) max. is possible.
This series requires less space and has greater EMI suppression effects.
- Different types with the same shape are available.
- Excellent in physical properties, such as terminal strength, flexure strength, soldering resistance and solderability.
- Applicable to both flow and reflow soldering.
- High impedance cover wide frequency ranges.
- YI series can be used in high current circuits due to its low DC resistance.
- Operating temperature: -55°C ~ +125°C (Including self-temperature).

■ Applications

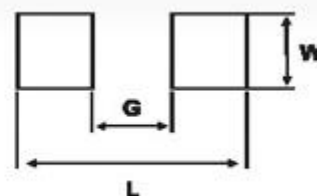
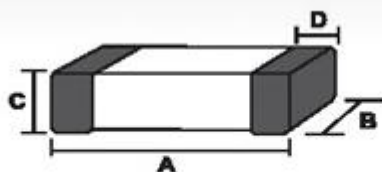
- Computers and peripheral devices, personal computers, VCR and cameras.
- Noise suppression in digital equipments, car stereo, car engines controllers and OA electronic instruments.
- Communication equipment.

■ Product Identification



- (1) : Type
- (2) : Dimensions
- (3) : Material Code
- (4) : Impedance
- (5) : Rated Current

Shapes and Dimensions (Unit: mm)



TYPE	A	B	C	D	L	W	G
YI201209	2.0±0.2	1.2±0.2	0.9±0.2	0.5±0.3	3.20	1.50	0.60

Electrical Requirements

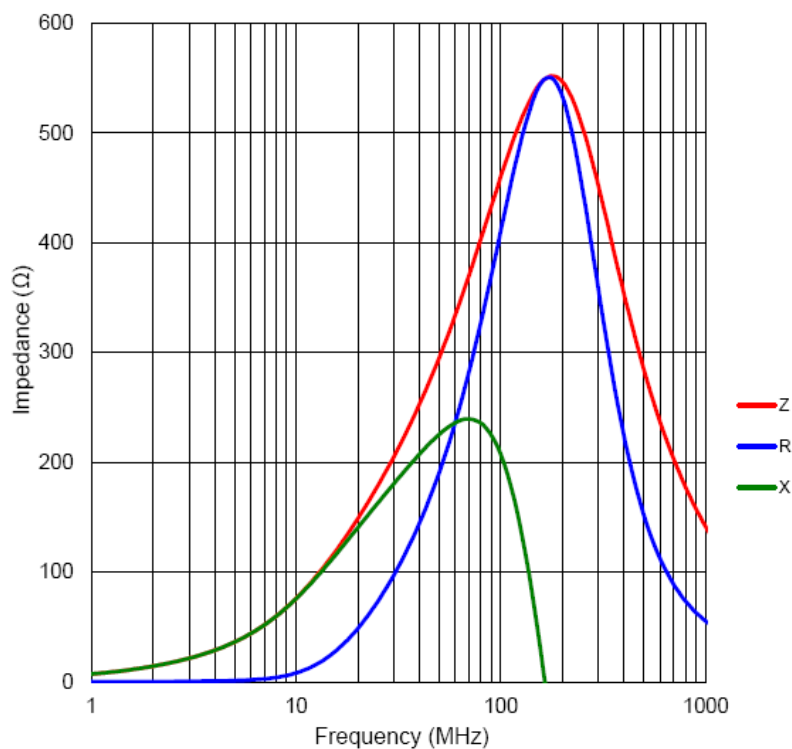
Part Number	Impedance(Ω) ±25%	Test Freq. (MHz)	DCR MAX. (mΩ)	Rating Current MAX.(A)
YI201209U471-3R0T	470	100	55	3.0

TEST INSTRUMENTS:

HP 4338A MILLIOHM METER

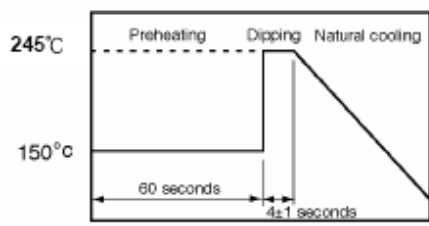
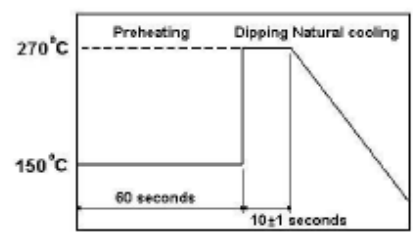
HP 4291B RF IMPEDANCE/MATERIAL ANALYZER

Impedance VS. Frequency characteristic



Reliability test

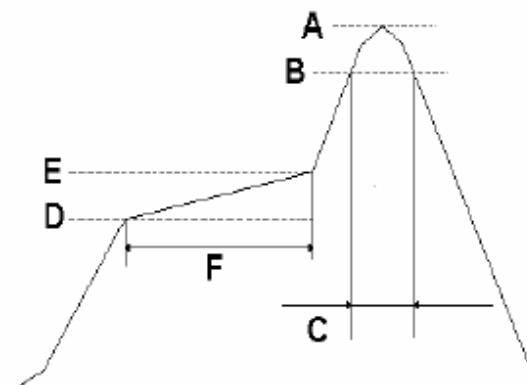
Item	Performance	Test condition
Operating temperature range	-55 °C to + 125 °C	
Storage temperature and umidity ranges	40 °C MAX., 70% RH MAX.	
Soldering heat resistance	The chip shall not be cracks. More than 75% of terminal electrode shall be covered with solder.	Preheat: 150 °C, 60 seconds Solder temperature : 270 ± 5 °C Flux: Rosin Dip time: 10 ± 1 seconds
Solderability	More than 90% of the terminal electrode shall be covered with new solder.	Preheat: 150 °C, 60 seconds Solder temperature: 245 ± 5 °C Flux: Rosin Dip time: 4 ± 1 seconds




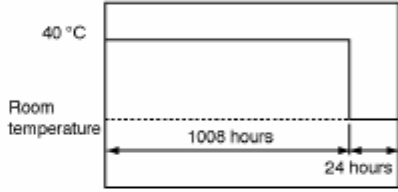
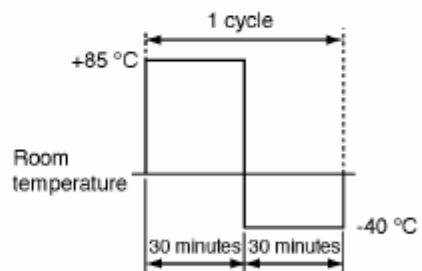
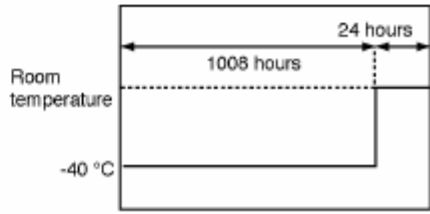
Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) **Lead-Free**

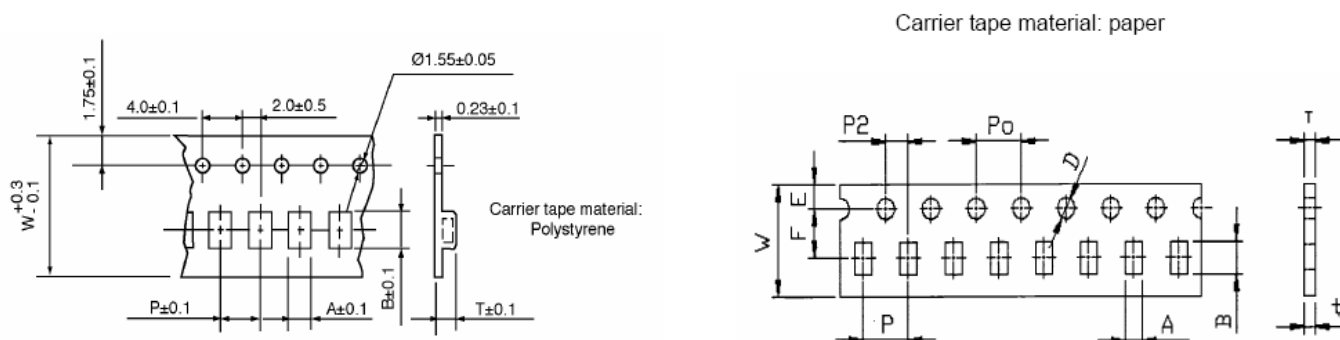
A	$260 \pm 5^{\circ}\text{C}$
B	$230 \pm 5^{\circ}\text{C}$
C	$30 \pm 10 \text{ sec}$
D	150°C
E	180°C
F	$90 \pm 30 \text{ sec}$



Reliability test

Item	Performance	Test condition
High temperature resistance	Appearance: Ferrite shall not be damaged. Impedance: Within±20% of the initial value.	Temperature: 85±2°C Testing time: 1008±12 hours Measurement: After placing for 24 hours min. 
Humidity resistance	Appearance: Ferrite shall not be damaged. Impedance: Within±20% of the initial value	Humidity: 90 to 95% RH Temperature: 40±2°C Testing time: 1008±12 hours Measurement: After placing for 24 hours min. 
Thermal Shock	Appearance: Cracking, chipping or any other defects harmful to the characteristics shall not be allowed. Impedance: Within±20% of the initial value	Temperature: -40°C, +85°C, kept stabilized for 30 minutes each Cycle: 100 cycles Measurement: After placing for 24 hours min. 
Low temperature storage life test	Appearance: Cracking, chipping or any other defects harmful to the characteristics shall not be allowed. Impedance: Within±20% of the initial value.	Temperature: -40±2°C Testing time: 1008±12 hours Measurement: After placing for 24 hours min. 

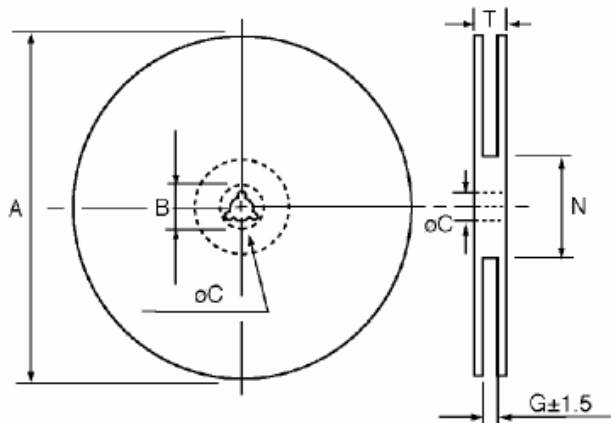
■ Taping Dimensions(Unit:mm)



Material:Paper						
TYPE	A	B	W	P	T	CHIPS/REEL
100505	0.62	1.12	8	2	0.60	10000
160808	1.10	1.90	8	4	0.95	4000
201209	1.50	2.30	8	4	0.95	4000
Material:Polystyrene						
TYPE	A	B	W	P	T	CHIPS/REEL
160808	1.01	1.80	8	4	1.02	4000
201209	1.42	2.25	8	4	1.04	4000
201212	1.50	2.35	8	4	1.45	3000
321611	1.88	3.50	8	4	1.27	3000
322513	2.77	3.42	8	4	1.55	2000
451616	1.93	4.95	12	4	1.93	2000
453215	3.66	4.95	12	8	1.85	1000
YA3216M4	1.88	3.50	8	4	1.40	3000

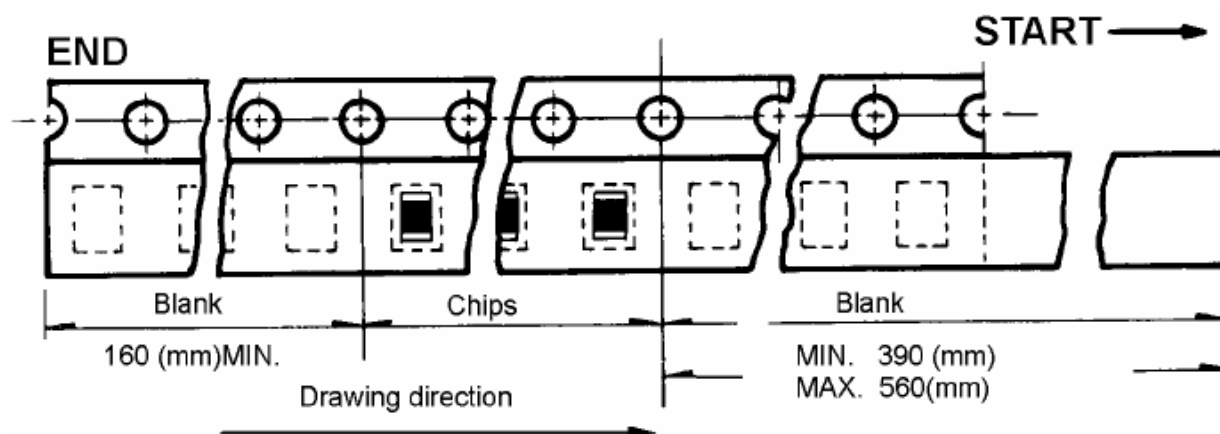
Reel Dimensions(Unit:mm)

Material:Paper, Plastic



TYPE	8mm	12mm
A	178±2	178±2
B	21.0±0.8	21.0±0.8
C	13.0±0.8	13.0±0.8
G	10.0	14.0
N	75	75
T	12.5	16.5

Direction of rolling



X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for [Ferrite Beads](#) category:

Click to view products by [YJYCOIN](#) manufacturer:

Other Similar products are found below :

[CZB1EGTTP700P](#) [CZB1JGTTD152P](#) [CZB2AFTTD800P](#) [CZB2AGTTD121P](#) [CZB2AGTTD601P](#) [CZB2BFTTE600P](#) [PE-0402FB121ST](#)
[DER0705-2.2](#) [NCB0603R301TR050F](#) [NCB-H1206B680TR300F](#) [CZB1JGTTD221P](#) [CZB1JGTTD600P](#) [CZB2AGTTD301P](#)
[CZB2BFTTE301P](#) [CZB2BFTTE601P](#) [4221R-1](#) [432703041971](#) [EMI0805R-600](#) [SBY100505T-100Y-N](#) [NCB-GH0402D121TR060F](#)
[NCB0402P301TR005F](#) [NCB0603R152TR030F](#) [NCB0805A121TR050F](#) [NCB0805A301TR070F](#) [NCB3312K900TR500F](#) [NCB-](#)
[H1206B101TR300F](#) [NCB0402P221TR030F](#) [NCB0805A102TR040F](#) [NCB-H0402P100TR200F](#) [NCB-H0603R121TR300F](#) [NCB-](#)
[H0805A220TR600F](#) [NCB-H1206B601TR200F](#) [CZB1JGTTD202P](#) [CBH160808W221T](#) [EMI1206R-600](#) [WLBD1005HCU330TL](#)
[WLBD2012HCU121TH](#) [WLBD2012HCU221TH](#) [WQBD1608HCU121TH](#) [WLBD1608K2U800TP](#) [74279230](#) [BMB2A0080AN4](#)
[SZ1608F470TF](#) [FBSHC0805-331-302R](#) [HFJ100505T-601Y-N](#) [HFY100505T-221Y-N](#) [SBY060303T-121Y-N](#) [BBPY00160808301Y00](#)
[SBY100505T-750Y-N](#) [BBPY00100505102Y00](#)